

## Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- 100% avalanche tested
- RoHS compliant

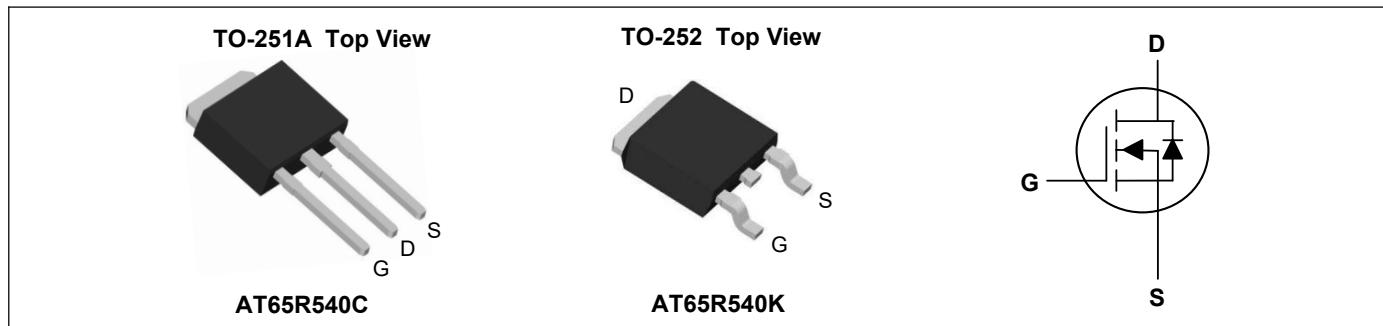
## Key Performance Parameters



Parameter	Value	Unit
$V_{DS}$	650	V
$R_{DS(ON),max}$	540	$m\Omega$
$I_D$	8	A
$Q_{g,typ}$	14.5	nC
$I_{DM}$	24	A

## Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



## Absolute Maximum Ratings( $T_c=25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current	$I_D @ T_c = 25^\circ C$	8	A
Continuous Drain Current	$I_D @ T_c = 100^\circ C$	5.2	A
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	24	A
Single Pulse Avalanche Energy <sup>2</sup>	EAS	185	mJ
Avalanche Current	$I_{AS}$	4	A
Repetitive Avalanche energy, $t_{AR}$ limited by $T_{Jmax}$	$E_{AR}$	0.4	mJ
MOSFET dv/dt ruggedness, $V_{DS} \leq 480V$	dv/dt	50	V/ns
Reverse diode dv/dt $V_{DS} \leq 480V$ , $I_{SD} = I_D$	dv/dt	15	
Total Power Dissipation ( $T_c=25^\circ C$ )	$P_D$	80	W
Storage Temperature Range	$T_{STG}$	-55 to 150	°C
Operating Junction Temperature Range	$T_J$	-55 to 150	°C

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-Ambient (Max)	$R_{\theta JA}$	62	°C/W
Thermal Resistance Junction-Case (Max)	$R_{\theta JC}$	1.56	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	650	---	---	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}$ , $I_D=4\text{A}$	---	480	540	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	2.5	3	3.5	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=650\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_C=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=650\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_C=125^\circ\text{C}$	---	---	100	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 30\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=20\text{V}$ , $I_D=4\text{A}$	---	5.5	---	S
Gate Resistance	$R_g$	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2	---	$\Omega$
Total Gate Charge	$Q_g$	$V_{\text{DS}}=480\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=8\text{A}$	---	14.5	---	nC
Gate-Source Charge	$Q_{\text{gs}}$		---	2.8	---	
Gate-Drain Charge	$Q_{\text{gd}}$		---	5.5	---	
Turn-On Delay Time	$T_{\text{d(on)}}$	$V_{\text{DD}}=380\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=12\Omega$ , $I_D=4\text{A}$	---	5.5	---	ns
Rise Time	$T_r$		---	3.5	---	
Turn-Off Delay Time	$T_{\text{d(off)}}$		---	55	---	
Fall Time	$T_f$		---	6.5	---	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	680	---	pF
Output Capacitance	$C_{\text{oss}}$		---	58	---	
Reverse Transfer Capacitance	$C_{\text{rss}}$		---	4	---	

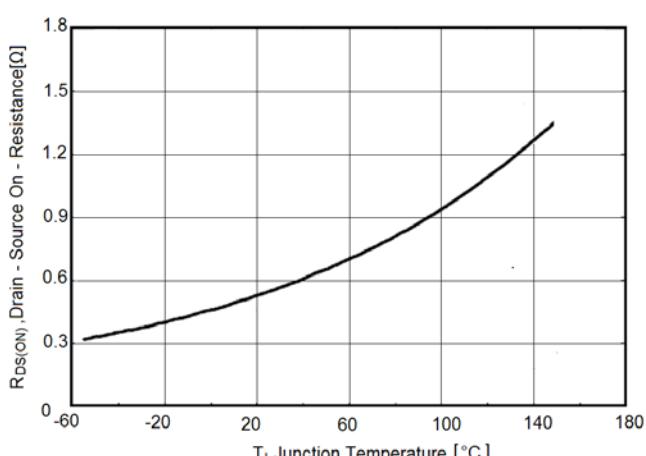
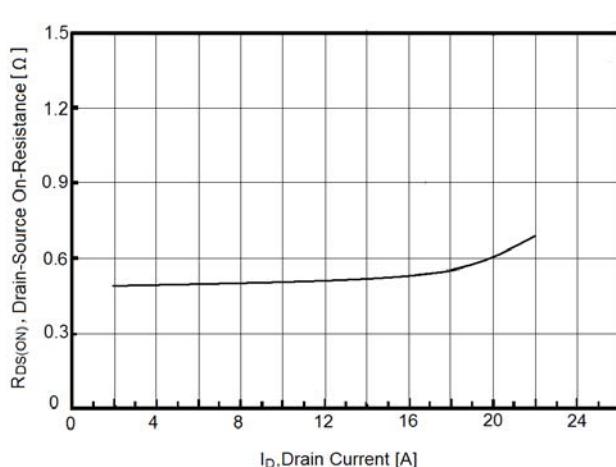
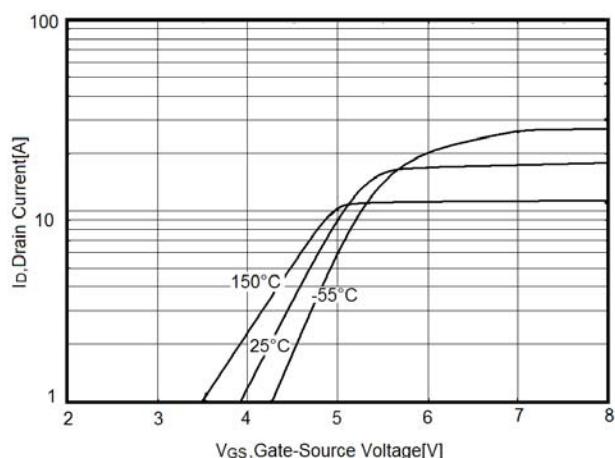
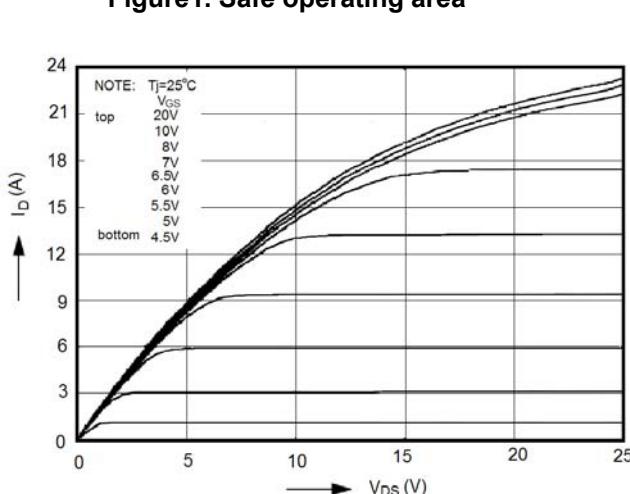
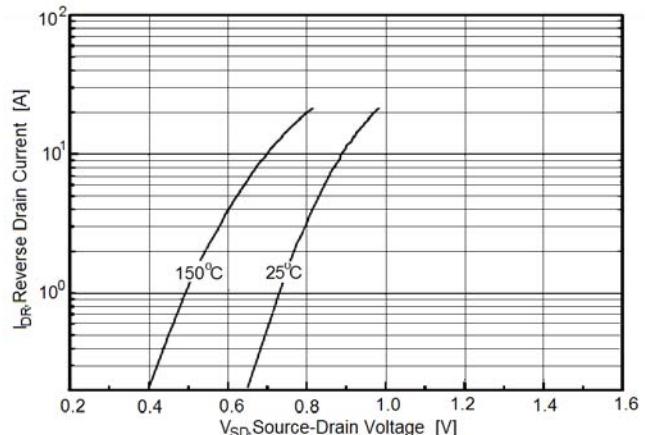
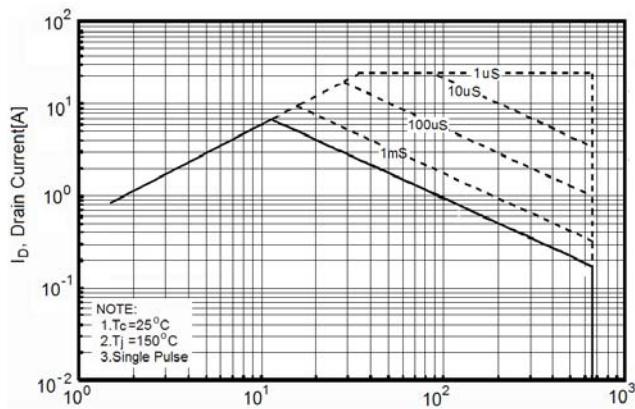
**Drain-Source Diode Characteristics**

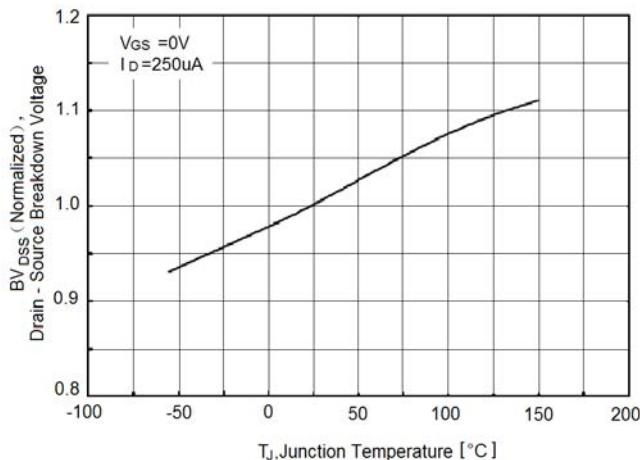
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Source-Drain Current(Body Diode)	$I_{\text{SD}}$	$T_C=25^\circ\text{C}$	---	---	8	A
Pulsed Source-Drain Current	$I_{\text{SDM}}$		---	---	23.4	A
Forward On Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}$ , $I_{\text{SD}}=8\text{A}$ , $T_J=25^\circ\text{C}$	---	0.9	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F=8\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	220	---	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		---	2.2	---	$\mu\text{C}$
Peak Reverse Recovery Current	$I_{\text{rrm}}$		---	20	---	A

**Note:**

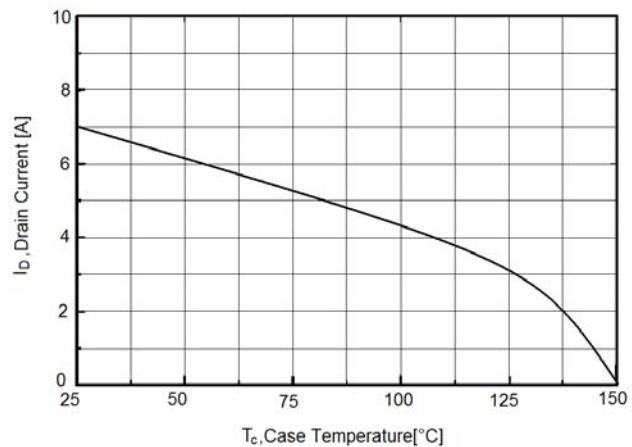
1. Repetitive Rating:Pulse width limited by maximum junction temperature
2.  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $R_G=25\Omega$

## Typical Characteristics

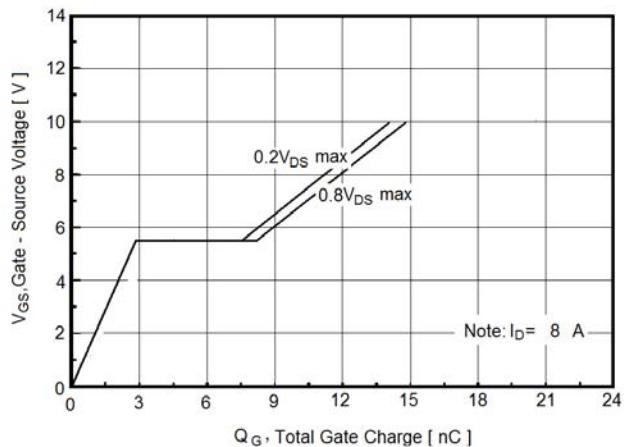




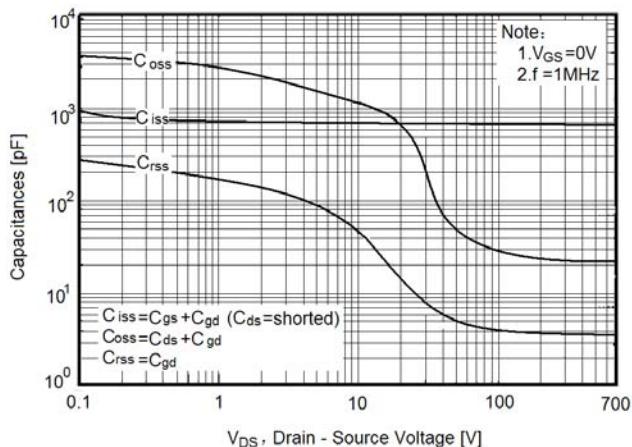
**Figure7.  $BV_{DSS}$  vs Junction Temperature**



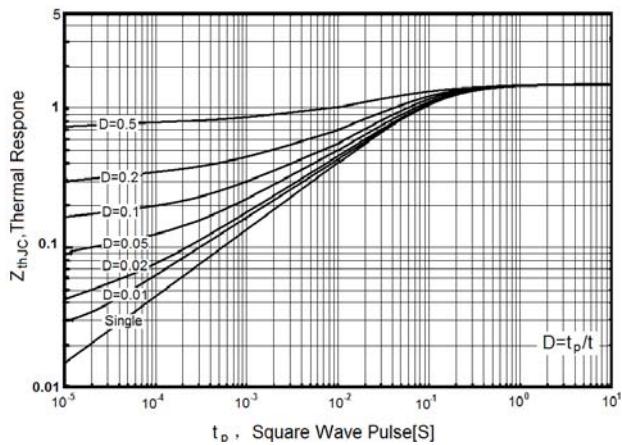
**Figure8. Maximum  $I_D$  vs Junction Temperature**



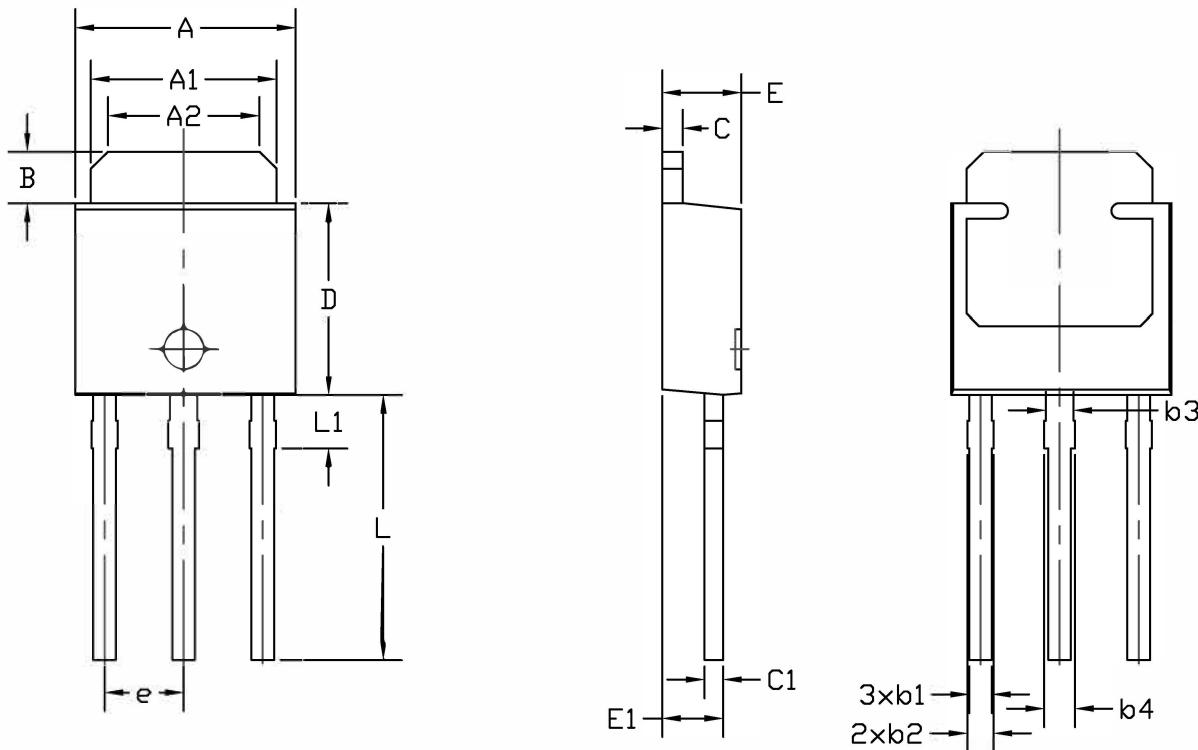
**Figure9. Gate charge waveforms**



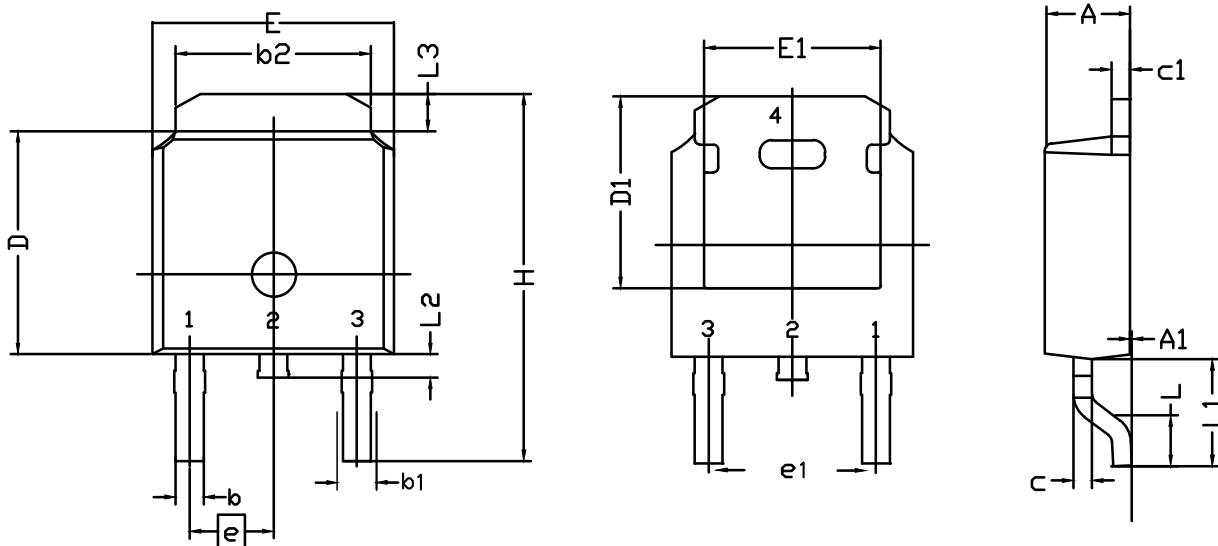
**Figure10. Capacitance**



**Figure11. Transient Thermal Impedance**

**TO-251A Package Outline Dimensions**


<b>Symbol</b>	<b>Dimensions (unit:mm)</b>			<b>Symbol</b>	<b>Dimensions (unit:mm)</b>		
	<b>Min</b>	<b>Typ</b>	<b>Max</b>		<b>Min</b>	<b>Typ</b>	<b>Max</b>
<b>A</b>	6.35	6.55	6.65	<b>C</b>	0.45	0.55	0.65
<b>A1</b>	5.20	5.35	5.50	<b>C1</b>	0.45	0.55	0.65
<b>A2</b>	4.20	4.35	4.50	<b>D</b>	5.40	5.55	5.70
<b>B</b>	1.35	1.50	1.65	<b>E</b>	2.20	2.30	2.40
<b>b1</b>	0.55	0.65	0.75	<b>e</b> 2.30 REF			
<b>b2</b>	0.60	0.70	0.85	<b>E1</b>	1.70	1.77	1.82
<b>b3</b>	0.80 REF			<b>L</b>	7.40	7.70	8.00
<b>b4</b>	0.90 REF			<b>L1</b>	1.55 REF		

**TO-252 Package Outline Dimensions**


<b>Symbol</b>	<b>Dimensions (unit:mm)</b>			<b>Symbol</b>	<b>Dimensions (unit:mm)</b>		
	<b>Min</b>	<b>Typ</b>	<b>Max</b>		<b>Min</b>	<b>Typ</b>	<b>Max</b>
<b>A</b>	2.20	2.30	2.38	<b>E</b>	6.40	6.60	6.731
<b>A<sub>1</sub></b>	0.00	0.10	0.20	<b>E<sub>1</sub></b>	4.40	--	--
<b>b</b>	0.64	0.76	0.89	<b>e</b>	2.286 BSC		
<b>b<sub>1</sub></b>	0.77	0.85	1.14	<b>e<sub>1</sub></b>	4.572 BSC		
<b>b<sub>2</sub></b>	5.00	5.33	5.46	<b>H</b>	9.40	10.00	10.40
<b>c</b>	0.458	0.508	0.610	<b>L</b>	1.40	1.52	1.77
<b>C<sub>1</sub></b>	0.458	0.508	0.620	<b>L<sub>1</sub></b>	--	2.743	--
<b>D</b>	5.98	6.10	6.223	<b>L<sub>2</sub></b>	0.60	0.80	1.01
<b>D<sub>1</sub></b>	5.20	5.25	5.38	<b>L<sub>3</sub></b>	0.90	1.06	1.25